

General Description

SSF201 is a small 8pin DFN packaged customized ASIC with configurable parameters. It supports frequency division and in-phase output function.

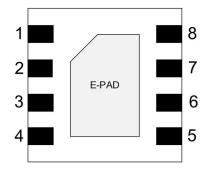
Features

- Power supply input: 2.3V~5.5V
- OUT1, 1x Push Pull Digital Output, 12.288Mhz output
- OUT2, 1x Push Pull Digital Output, 12.288Mhz output
- GND Power Ground
- OUT3, 1x Push Pull Digital Output 192Khz output
- NC Not Connected, Internal pull-down 1M
- IN Digital input with Schmitt, Internal pull-down 1M, 24.576Mhz input
- DFN 8 Package

Applications

- Ultra low power consumption
- Pb Free and RoHS Compliant and Halogen Free

Pin Configurations

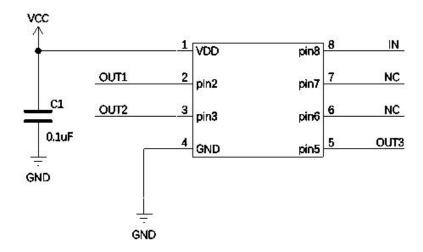


2.0mm x 2.0mm 8 Pin DFN Top View

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Block Diagram



Note:

- 1. Voltage on any pin must be with in GND to VDD.
- 2. ESD protect is must be considered on all Pins which connected to external interface.

Pin name

Pin	Pin	ТҮРЕ	Function
1	VDD	Power	Power supply input, 2.3V~5.5V
2	OUT1	1x Push Pull Digital Output	12.288Mhz output.
3	OUT2	1x Push Pull Digital Output	12.288Mhz output.
4	GND	Power	Ground
5	OUT3	1x Push Pull Digital Output	192Khz output.
6	NC	Not Connected	Internal pull-down 1M
7	NC	Not Connected	Internal pull-down 1M
8	IN	Digital input with Schmitt	Internal pull-down 1M, 24.576Mhz input.

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Absolute Maximum Ratings

Parameter	Min.	Max.	Unit
Supply Voltage on VDD to GND	-0.3	7	V
Maximum Voltage Input to Pins	-0.3	7	V
VDD to GND Maximum DC Current		90	mA
Input Leakage Current		1000	nA
Storage Temperature Range	-65	150	°C
Junction Temperature		150	°C
ESD Protection (HBM)	2000		V
ESD Protection (CDM)	500		V
Moisture Sensitivity Level (MSL)		1	

Customize Electrical Characteristics

VDD = $3.3V\pm10\%$, Temp= 25° C

Symbol	Parameter	Condition/Note	Min.	Тур.	Max.	Unit
lα	Quiescent Current	Static inputs and floating outputs		0.1		μΑ

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Electrical Characteristics

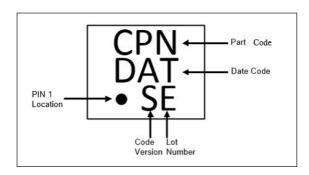
VDD =3.3V±10%, Temp: -40~85°C

Symbol	Parameter	Condition/Note	Min.	Тур.	Max.	Uni
V _{DD}	Supply Voltage		1.71	3.3	5.5	V
T _A	Operating Temperature		-40	25	85	°C
C _{VDD}	Capacitor Value at VDD			0.1		μF
I _{IH}	HIGH-Level Input Current	Logic Input PINs; V _{IN} = VDD	-1.0		1.0	μΑ
I _{IL}	LOW-Level Input Current	Logic Input PINs; V _{IN} = 0V	-1.0		1.0	μΔ
POR						
PON_{THR}	Power On Threshold	VDD Level Required to Start Up	1.67	1.80	1.92	V
POFF _{THR}	Power Off Threshold	VDD Level Required to Switch Off	0.95	1.25	1.54	V
T_{SU}	Startup Time	From VDD rising past PON _{THR}		1.2	1.6	m:
I _{stand_by}		T=+25℃		97		n/
O PIN						
	HIGH-Level Input Voltage	Logic Input	1.90			٧
V_{IH}		Logic Input with Schmitt Trigger	2.11			٧
		Low-Level Logic Input	0.92			V
		Logic Input	0.92 1.30 1.10 0.77	1.30	٧	
V_{IL}	LOW-Level Input Voltage	Logic Input with Schmitt Trigger			1.16	V
		Low-Level Logic Input	c Input 1.30 c Input with Schmitt Trigger 1.16 -Level Logic Input 0.77 c Input with Schmitt Trigger 0.45	0.77	V	
V_{HYS}	SchmittTrigger Hysteresis Voltage	Logic Input with Schmitt Trigger		0.45		V
I _{LKG}	Input leakage (Absolute Value)			1	1000	n <i>A</i>
M	HIGH-Level Outpu Voltage	Push-Pull, I _{OH} = 3 mA, 1X Drive	2.60			٧
V _{OH}		Push-Pull, I _{OH} = 3 mA, 2X Drive	2.80	1.71 3.3 -40 25 0.1 -1.0 1.67 1.80 0.95 1.25 1.2 97 1.90 2.11 0.92 0.45 1 2.60 1 2.60 0.1 1.2 1.2 1.2 1.2		٧
		Push-Pull, I _{OL} = 3 mA, 1X Drive		3.3 5.5 25 85 0.1 1.0 1.0 1.0 1.80 1.92 1.25 1.54 1.2 1.6 97	0.25	V
	LOW-Level Output Voltage	Push-Pull, I _{OL} = 3 mA, 2X Drive			0.22	V
V _{OL}		Open Drain, I _{OL} = 3 mA, 1X Drive			0.12	V
		Open Drain, I _{OL} = 3 mA, 2X Drive			0.089	V
	HIGH-Level Output Pulse Current (see Note)	Push-Pull, V _{OH} = 2.4 V , 1X Drive	5			m
I _{OH}		Push-Pull, V _{OH} = 2.4 V, 2X Drive	10			m
	LOW-Level Output Pulse Current (see Note)	Push-Pull, V _{OL} = 0.4 V, 1X Drive	5			m
I _{OL}		Push-Pull, V _{OL} = 0.4 V, 2X Drive				m
		Open Drain, V _{OL} = 0.4 V, 1X Drive	15			m
		Open Drain, V _{OL} = 0.4 V, 2X Drive	30			m

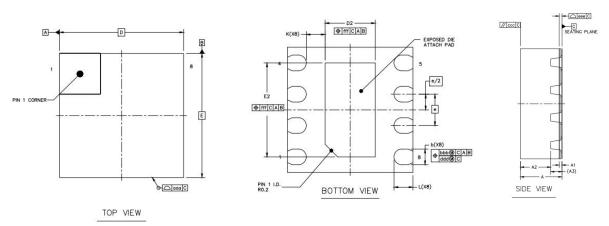
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Package Top Marking



Package Drawing and Dimensions



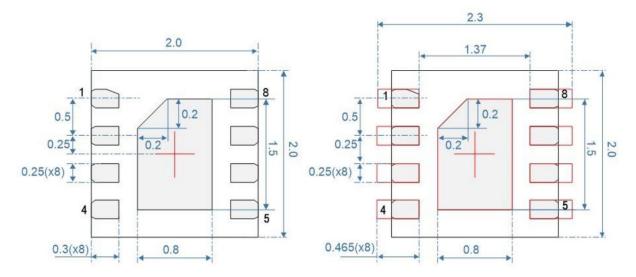
		SYMBOL	MIN	NOM	MAX	
TOTAL THICKNESS		A	0.7	0.75	0.8	
STAND OFF		A1	0	0.02	0.05	
MOLD THICKNESS		A2		0.55		
L/F THICKNESS		A3	0.203 REF			
LEAD WIDTH		ь	0.2	0.25	0.3	
BODY SIZE	×	D	2 BSC			
BODT SIZE	Y	E	2 BSC			
LEAD PITCH	1177	e		0.5 BSC		
EP SIZE	×	D2	0.7	0.8	0.9	
EP SIZE	Y	E2	1.4	1.5	1.6	
LEAD LENGTH		L	0.2	0.3	0.4	
LEAD TIP TO EXPOSE	D PAD EDGE	к	0.3 REF			
PACKAGE EDGE TOLERANCE		aaa	0.1			
MOLD FLATNESS		ccc	0.1			
COPLANARITY		eee	0.05			
LEAD OFFICET		bbb	0.1			
LEAD OFFSET		ddd	0.05			
EXPOSED PAD OFFSET		fff		0.1		
		+ +				

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Recommended Land Patter

Unit: mm



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